

# **JEDEC/IPC JOINT PUBLICATION**

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## **Current Tin Whiskers Theory and Mitigation Practices Guideline**

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The material in this joint standard was developed by the  
JEDEC JC-14.1 Committee on Reliability Test Methods for Packaged Devices  
and the IPC Tin Whiskers Guideline Task Group (5-23e).

For Technical Information Contact:

JEDEC Solid State Technology Association  
2500 Wilson Boulevard, Suite 220  
Arlington, VA 22201  
Phone (703) 907-7500  
Fax (703) 907-7583

IPC  
3000 Lakeside Drive, Suite 309S  
Bannockburn, Illinois 60015-1219  
Tel (847) 615-7100  
Fax (847) 615-7105

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or call (703) 907-7559